

SAW Components

Data Sheet B3731





SAW Components

Passivation layer: Elpas

B3731 315,00 MHz

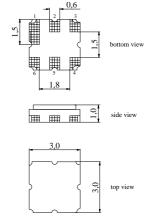
Low-loss Filter

Data Sheet

Features

(SMT)

Ceramic package DCC6E



Terminals

Ni, gold plated

typ. dimensions in mm, approx. weight 0,037 g

Pin configuration¹⁾

1 Input (recommended) or Input Ground

RF low-loss filter for remote control receivers

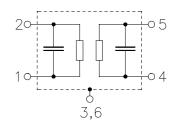
Balanced and unbalanced operation possible

Compliant to EU RoHs Directive (2002/95/EC)
Lead free soldering compatible with J - STD20C

AEC-Q200 qualified component family

■ Package for Surface Mounted Technology

- 2 Input Ground (recommended) or Input
- 4 Output (recommended) or Output Ground
- 5 Output Ground (recommended) or Output
- 3,6 to be grounded



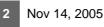
Туре	Ordering code	Marking and package according to	Packing according to		
B3731	B39321-B3731-H110	C61157-A7-A143	F61074-V8168-Z000		

Electrostactic Sensitive Device (ESD)

Maximum ratings

Operable temperature range	T _A	-45/+120	°C	
Storage temperature range	$T_{\rm stg}$	-45/+120	°C	
DC voltage	V _{DC}	6	V	
Source power	P_S	10	dBm	source impedance 50 Ω

¹⁾ The recommended pin configuration usually offers best suppression of electrical crosstalk. The filter characteristics refer to this configuration.

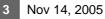




Low-loss Filter	315,00 MH				
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Characteristics					
Reference temperature: T _A	= -45 .	+95°C			
	and matching network t.b.d.				
Terminating load impedance: $Z_{\rm L}$	= 50 Ω	and match	ning network	k t.b.d.	
		min.	typ.	max.	
Center frequency	f _C	_	315,00	—	MHz
(center frequency between 3 dB points)					
Minimum insertion attenuation	α_{min}				
including loss in matching elements ($Q_{L} = 42$)	_	2,4	3.2	dB	
excluding loss in matching elements			1,4	2,2	dB
Pass band (relative to α_{min})					
314,85 315,15 MHz		_	0,6	2,0	dB
314,82 315,18 MHz		_	0,8	3,0	dB
314,78 315,22 MHz		_	1,2	6,0	dB
Filter bandwidth					
$\alpha_{rel} \leq 3 \text{ dB}$		0,57	0,63	0,69	MHz
Relative attenuation (relative to α_{min})	α_{rel}				
10,00 295,00 MHz		48	53	—	dB
295,00 307,00 MHz		43	48	—	dB
307,00 312,00 MHz		32	36	—	dB
312,00 314,00 MHz		25	29	—	dB
316,00 325,00 MHz		10	14	—	dB
325,00 336,00 MHz		38	43	—	dB
336,00 370,00 MHz		42	46	—	dB
370,00 600,00 MHz		52	57	—	dB
600,001500,00 MHz		60	65	—	dB
1500,002500,00 MHz		55	60	—	dB
Impedance for pass band matching ¹⁾					
Input: $Z_{\rm IN} = R_{\rm IN} C_{\rm IN}$		_	610 2,2	_	Ω pl
Output: $Z_{OUT} = R_{OUT} C_{OUT}$		_	610 2,2	_	Ω pF

¹⁾ Impedance for passband matching bases on an ideal, perfect matching of the SAW filter to source- and to load impedance (here 50 Ohm). After the SAW filter is removed and input impedance into the input matching / output matching network is calculated.

The conjugate complex value of these characteristic impedances are the input and output impedances for flat passband. For more details, we refer to EPCOS application note #4.

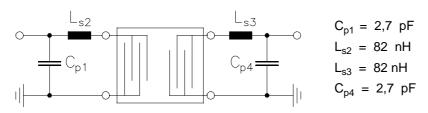




Low-loss Filter

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Matching network to 50 Ω (element values depend on pcb layout and equivalent circuit)



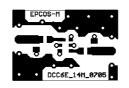
Minimising the crosstalk

For a good ultimate rejection a low crosstalk is necessary. Low crosstalk can be realised with a good RF layout. The major crosstalk mechanism is caused by the "ground-loop" problem.

Grounding loops are created if input-and output transducer GND are connected on the top-side of the PCB and fed to the system grounding plane by a common via hole. To avoid the common ground path, the ground pin of the input- and output transducer are fed to the system ground plane (bottom PCB plane) by their own via hole. The transducers' grounding pins should be isolated from the upper grounding plane.

A common GND inductivity of 0.5nH degrades the ultimate rejection (crosstalk) by 20dB.

The optimised PCB layout, including matching network for transformation to 50 Ohm, is shown here. In this PCB layout the grounding loops are minimised to realise good ultimate rejection.



Optimised PCB layout for SAW filters in DCC6E package, pinning 1,4 (top side, scale 1:1)

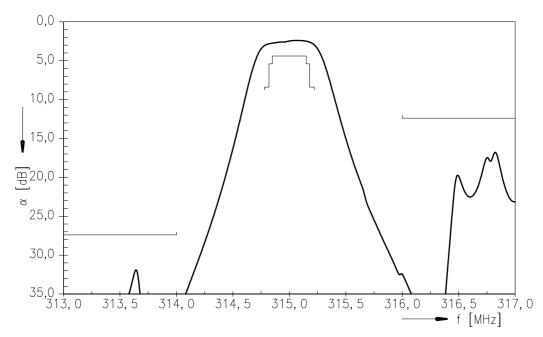
The bottom side is a copper plane (system ground area). The input and output grounding pins are isolated and connected to the common ground by separated via holes.

For good contact of the upper grounding area with the lower side it is necessary to place enough via holes.

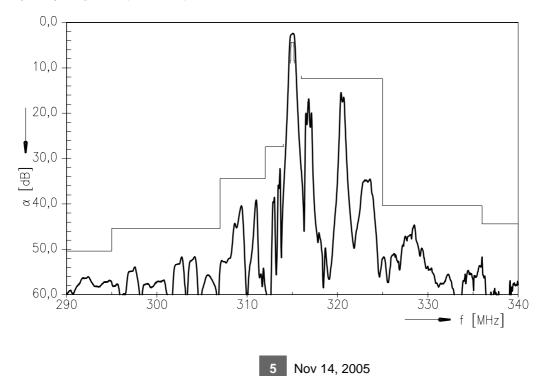


Data Sheet

Frequency response



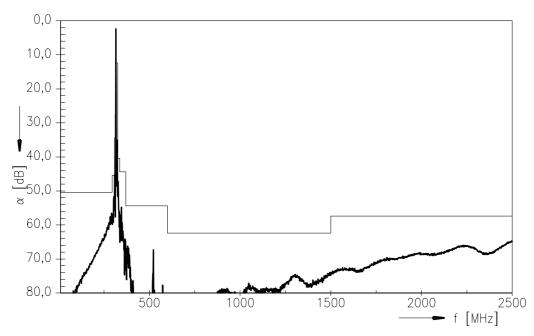
Frequency response (wideband)





Data Sheet

Frequency response (ultimate rejection)



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